

Automatic Deep Access Wire Bonder

Model: SA-DAWB-6000B

SA-DAWB-6000B features real-time deformation and ultrasonic monitoring, precise tail and loop control. It supports deep-access capillaries with an assist camera for easy head maintenance. Ideal for microwave devices, lasers, optical communication, sensors, MEMS and RF components, it offers high-accuracy, reliable microelectronic bonding.



Feature

- Large welding working range
- Real-time deformation monitoring
- Real-time ultrasonic energy monitoring
- Piezoelectric ultrasonic motor tail wire control mechanism
- Compatible with 16mm and 19mm capillaries
- Fixed-length & fixed-height loop control capability
- HD vision assistant tool for bonder head maintenance

Application

- Microwave components
- Lasers
- Optical communication devices
- Sensors
- MEMS
- RF modules
- SAW devices
- Power devices
- Discrete devices

Specifications:

Parameter	Descriptions
Bonding Accuracy	$\pm 3 \mu\text{m}@3\sigma$
Bonding Area	X-axis: 305 mm, Y-axis: 457 mm, rotation range: 0~180°
Ultrasonic	0~4 W precise control with stepped flexible energy output
Loop Control	Fully programmable
Cavity Depth	12mm(max.)
Bonding Force	0~220g
Capillary Length	16mm/19mm
Bonding Wire Type	Gold wire(18~75 μm), copper wire (18~75 μm), selected alloy wires
Bonding Speed	$\geq 5\text{wires/s}$
Operating System	Windows
Weight	1.2T
Input Voltage	220V $\pm 10\%$ @50~60Hz
Power	2KW
Compressed Air Pressure	$\geq 0.35\text{MPa}$
Size(L×W×H)	1500mm×1000mm×1700mm